

We Claim:

1. A method for producing a plurality of electronic devices having external contact elements, which comprises the steps of:

providing a metal plate having a plurality of device positions;

forming cutouts in a top side of the metal plate at the device positions, a contour of the cutouts corresponding to a form of external sections of the external contact elements;

applying a mask to the top side of the metal plate, the mask having openings formed therein in a region of the cutouts;

depositing, via one of chemical deposition and electrodeposition, at least one core material in the cutouts and in the openings resulting in a formation of metallic bulges at edges of the openings in the mask;

applying a metallic material to the metallic bulges;

removing the mask;

disposing semiconductor chips having contact areas at the device positions;

electrically connecting the contact areas of the semiconductor chips to at least the metallic bulges;

coating the metal plate with a plastic housing composition resulting in a composite body being produced;

removing the metal plate; and

separating the composite body into individual ones of the electronic devices.

2. The method according to claim 1, which further comprises:

applying a covering mask to the metal plate as the mask; and

etching the metal plate, through the openings of the covering mask, for forming the cutouts, the covering mask is subsequently used as a protective mask for the chemical deposition or the electrodeposition of the metallic bulges.

3. The method according to claim 1, which further comprises forming the cutouts in the metal plate using one of an embossing tool and a rolling tool.

4. The method according to claim 1, which further comprises carrying out the chemical deposition or the electrodeposition in two stages including the steps of:

depositing a solder alloy as an external core material for the external sections of the external contact elements; and

depositing a metal alloy as an internal core material, having a higher melting point than the solder alloy, for internal sections of the external contact elements.

5. The method according to claim 1, which further comprises continuing the chemical deposition or the electrodeposition until the metallic bulges are rivet-head-type bulges or mushroom-cap-type bulges formed at the edges of the openings of the mask.

6. The method according to claim 1, which further comprises:

providing additional patterned openings in the mask for the chemical deposition or the electrodeposition at the device positions; and

depositing at least one of conductor tracks and semiconductor chip islands in the openings.

7. An electronic device, comprising:

a plastic housing having an external contact side; and
external contact elements projecting from said plastic housing
on said external contact side, each of said external contact
elements having an internal section with an internal core and
an internal coating, said internal section being disposed in
said plastic housing, each of said external contact elements
having an external section with an external core and an
external coating, said external section projecting from said
plastic housing, and said internal section having an anchoring
region and said external section having at least one external
contact region tapering away from said external contact side.

8. The electronic device according to claim 7, wherein said
external section has a plurality of external contact regions
adjoining one another.

9. The electronic device according to claim 7, wherein said
external contact region of at least one of said external
contact elements has a substantially conical shape, a
substantially pyramidal shape, or a substantially
hemispherical shape.

10. The electronic device according to claim 7, wherein said external core and said internal core are formed of an identical core material.

11. The electronic device according to claim 7, wherein said external coating is formed of a solder alloy.

12. The electronic device according to claim 7, wherein said external core is formed of a solder alloy and said internal core is formed of a metal or a metal alloy having a higher melting point than a flow temperature of said solder alloy.

13. The electronic device according to claim 7, wherein said internal section has an internal flat conductor, and said external section has an external flat conductor with an emplaced said external contact region.

14. The electronic device according to claim 10, wherein said identical core material is selected from the group consisting of nickel, copper, nickel alloy, copper alloy, and an alloy containing nickel and copper.